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Anja Fink
7-27-02

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

BOX AF

In re the Application of:

Norio FUKASAWA et al

Serial Number: **09/029,608**

Group Art Unit: **2814**

Filed: **May 15, 1998**

Examiner: **Graybill, D.**

For: **METHOD AND MOLD FOR MANUFACTURING SEMICONDUCTOR DEVICE,
SEMICONDUCTOR DEVICE AND METHOD FOR MOUNTING THE DEVICE**

AMENDMENT AFTER FINAL REJECTION

BOX AF

Commissioner for Patents
Washington, D.C. 20231

January 18, 2002

Sir:

In response to the Office Action dated October 19, 2001, please amend the above-identified application as follows:

IN THE CLAIMS:

Please cancel claims 18, 19, 36, 41-43, 82, 91, 95-102, 113 and 114 without prejudice or disclaimer.

Please amend claims 109-111, 115-117, 119, 122, 123 and 129 as follows:

109. (Amended) A semiconductor device comprising:

a semiconductor element having a surface on which protruding electrodes are formed;

a resin layer formed on the surface of the semiconductor element so as to seal the protruding

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electrodes except end portions thereof; and

